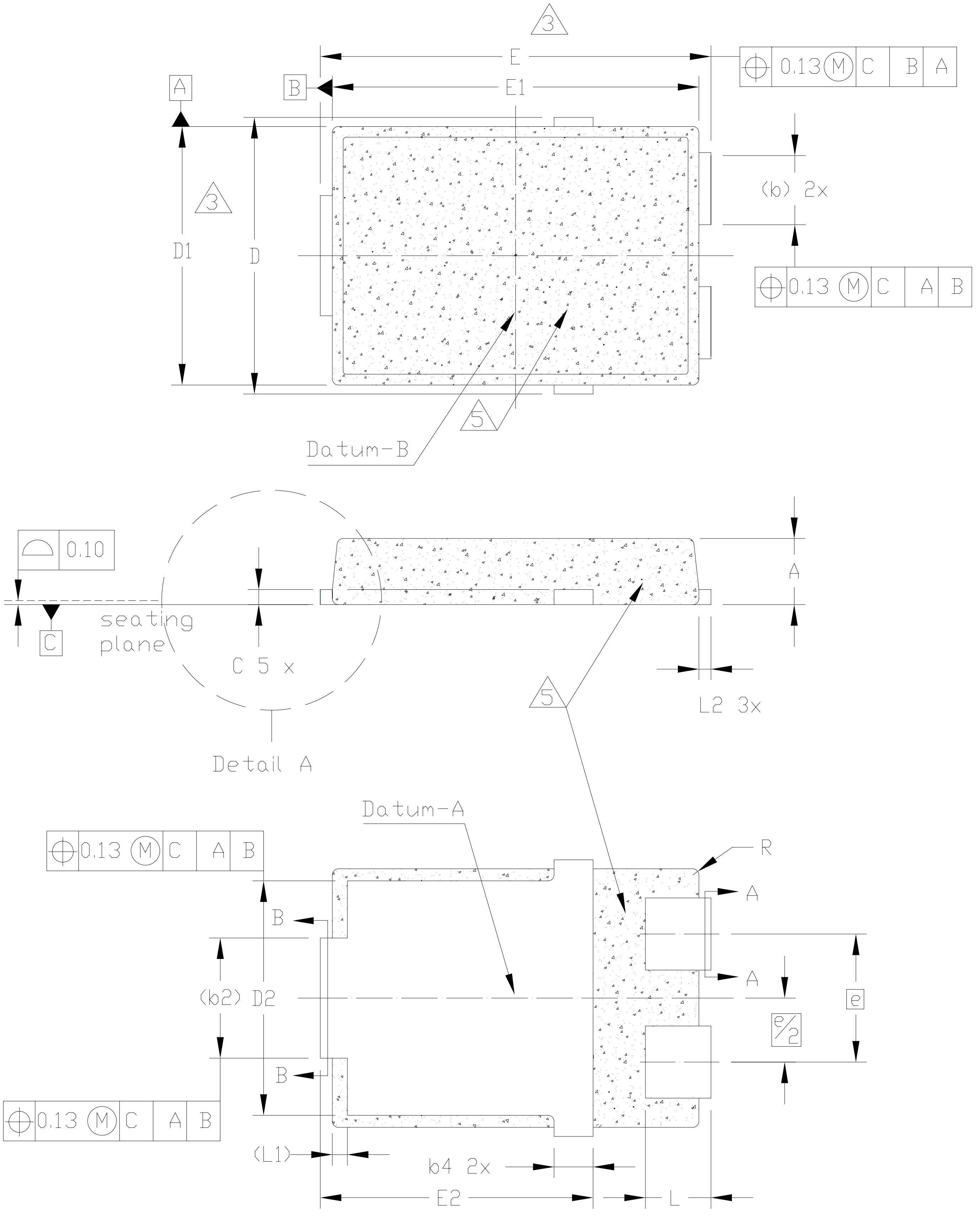
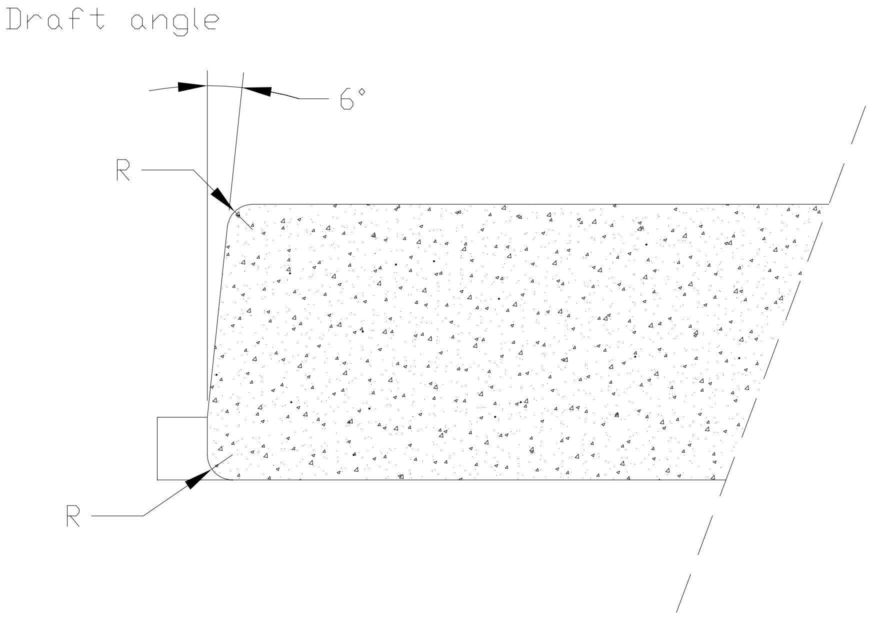


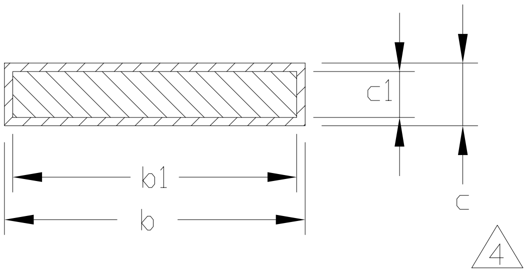
JEDEC
SOLID STATE PRODUCT
OUTLINES

THIS ***REGISTERED OUTLINE*** Has been prepared by the JEDEC JC-11 Committee and reflects a product with anticipated usage in the Electronics industry, Changes are likely to occur.

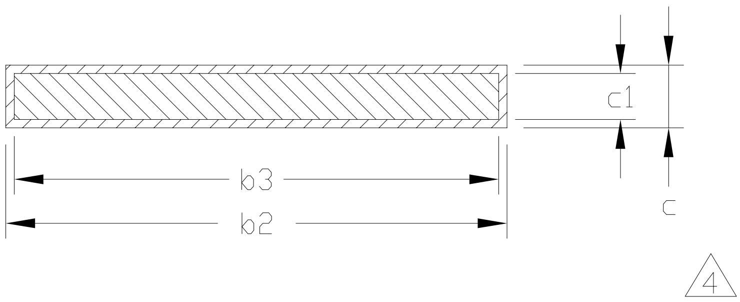
TITLE	PACKAGE DESIGNATOR	ISSUE	DATE	ITEM #	SHEET
SMALL OUTLINES PLASTIC SURFACE MOUNT PACKAGE	T-PSON-3	A	Jan. 2006	TO-277	1 OF 3



Detail A



Section A-A
(terminal cross-section)



Section B-B
(terminal cross-section)

JEDEC SOLID STATE PRODUCT OUTLINES	TITLE:	ISSUE	DATE	ITEM #	SHEET
	SMALL OUTLINES PLASTIC SURFACE MOUNT PACKAGE	A	Jan. 2006	TO-277	2 OF 3

Symbol	Min	Nom	Max
A	1.00	1.10	1.20
b	1.00	1.20	1.40
b1	1.00	1.20	1.35
b2	1.85	2.05	2.25
b3	1.80	2.00	2.15
b4	0.25	0.65	1.00
c	0.15	0.25	0.40
c1	0.15	0.25	0.35
D	4.45	4.60	4.75
D1	4.25	4.30	4.35
D2	3.75	3.95	4.15
E	6.35	6.50	6.65
E1	6.05	6.10	6.15
E2	4.40	4.60	4.80
e	--	2.10 BSC	--
L	0.90	1.10	1.25
L1	--	0.25 REF	--
L2	0.15	0.20	0.35
R	--	0.10REF	--
Note	1, 2		
Ref.	--		
Issue	DRAFT		

NOTE:

1 - Dimensioning and torlerancing per ASME Y14.5M-1994.

2 - All dimensions are in MILLIMETERS, angles are in degrees.

△3 - Dimensions D1 and E1 do not include mold flash, mold flash shall not exceed 0.13 mm per side.

△4 - Dimensions b1,b3 and c1 apply to base metal only,
Dimensions b,b2 and c apply to plated leads,
Dimensions b,c,b1,b2,b3,c1 to be measured on flat section of the lead, between 0.13 and 0.25 mm from lead tip.

△5 - Stipple area indicates molding compound.

JEDEC SOLID STATE PRODUCT OUTLINES	TITLE: SMALL OUTLINES PLASTIC SURFACE MOUNT PACKAGE	ISSUE A	DATE Jan. 2006	ITEM # TO-277	SHEET 3 OF 3

Initial Issue: A	Date: 1/19/06	JC11 Item number: 10-436

Change Record History

Issue: A	Date: 1/19/06	Item Number: 11.10-436
Description of Changes		
Outline creation		